



MICROCHIP

QUALIFICATION PLAN

PCN #: JAON-01PHJW963

Date

April 21, 2016

Qualification of MTAI assembly site for selected products available in 64L QFN (9x9x0.9mm) package with 311x311 and 291x291 leadframe paddle size.

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Purpose: _____ Qualification of MTAI assembly site for selected products available in 64L QFN (9x9x0.9mm) package with 311x311 and 291x291 leadframe paddle size.

CCB No.: _____ 2628

Misc.	Assembly site	MTAI
	BD Number	BDM-000748 rev.A
	MP Code (MPC)	WAAA17R4XEEL
	Part Number (CPN)	PIC32MZ2048ECH064-I/MR
Lead-Frame	Paddle size	311x311 mils
	Material	C194
	Surface	Bare Cu DAP (with BOT)
	Treatment	N/A
	Process	Etched
	Lead-lock	No
	Part Number	10106408
	Lead Plating	Matte Tin
Bond Wire	Material	Au
Die Attach	Part Number	3280
	Conductive	Yes
MC	Part Number	G700LTD
PKG	PKG Type	QFN
	Pin/Ball Count	64
	PKG width/size	9x9 mm
Die	Die Thickness	11 mils
	Die Size	217.7 x 228.9 mils

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	Special Instructions
Wire Bond Pull - WBP	Mil. Std. 883-2011	5	0	3	24	0 fails after TC	5	30 bonds from a minimum of 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001	5	0	3	24	0	5	30 bonds from a minimum of 5 devices.
Wire Sweep		5	0	3	15	0		Required for any reduction in wire bond thickness.
External Visual	Mil. Std. 883-2009/2010	All devices prior to submission for qualification testing	0	3	ALL	0	5	
HTSL (High Temp Storage Life)	+175 C for 504 hours or 150°C for 1008 hrs. Electrical test pre and post stress at +25°C and hot temp.85°C,	45	5	1	50	0	10	Must be in progress at time of package release to production, but completion is not required for release to production.
Preconditioning - Required for surface mount devices	+150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020D for package type; Electrical test pre and post stress at +25°C. MSL1 @ 260°C	231	15	3	738	0	15	Spares should be properly identified. 77 parts from each lot to be used for HAST, Autoclave, Temp Cycle test.
HAST	+130°C/85% RH for 96 hours or 110°C/85%RH for 264 hours. Electrical test pre and post stress at +25°C and hot temp.	77	5	3	246	0	10	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Unbiased HAST	+130°C/85% RH for 96 hrs or +110°C/85% RH for 264 hrs. Electrical test pre and post stress at +25°C.	77	5	3	246	0	10	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Temp Cycle	-65°C to +150°C for 500 cycles. Electrical test pre and post stress at hot temp; 3 gram force WBP, on 5 devices from 1 lot, test following Temp Cycle stress.	77	5	3	246	0	15	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.

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Affected Catalog Part Numbers (CPN)

PCN_JAON-01PHJW963
CATALOG_PART_NBR
DSPIC33EP512GP806-E/MR
DSPIC33EP512GP806-I/MR
DSPIC33EP512GP806T-E/MR
DSPIC33EP512GP806T-I/MR
DSPIC33EP512MC806-E/MR
DSPIC33EP512MC806-I/MR
DSPIC33EP512MC806T-E/MR
DSPIC33EP512MC806T-I/MR
DSPIC33FJ128GP206A-E/MR
DSPIC33FJ128GP206A-I/MR
DSPIC33FJ128GP206AT-E/MR
DSPIC33FJ128GP206AT-I/MR
DSPIC33FJ128GP306A-E/MR
DSPIC33FJ128GP306A-I/MR
DSPIC33FJ128GP306AT-E/MR
DSPIC33FJ128GP306AT-I/MR
DSPIC33FJ128GP706A-E/MR
DSPIC33FJ128GP706A-H/MR
DSPIC33FJ128GP706A-I/MR
DSPIC33FJ128GP706AT-E/MR
DSPIC33FJ128GP706AT-H/MR
DSPIC33FJ128GP706AT-I/MR
DSPIC33FJ128MC506A-E/MR
DSPIC33FJ128MC506A-H/MR
DSPIC33FJ128MC506A-I/MR
DSPIC33FJ128MC506AT-E/MR
DSPIC33FJ128MC506AT-H/MR
DSPIC33FJ128MC506AT-I/MR
DSPIC33FJ128MC706A-E/MR
DSPIC33FJ128MC706A-H/MR
DSPIC33FJ128MC706A-I/MR
DSPIC33FJ128MC706AT-E/MR
DSPIC33FJ128MC706AT-H/MR
DSPIC33FJ128MC706AT-I/MR
DSPIC33FJ64GP206A-E/MR
DSPIC33FJ64GP206A-I/MR
DSPIC33FJ64GP206AT-E/MR
DSPIC33FJ64GP206AT-I/MR
DSPIC33FJ64GP306A-E/MR
DSPIC33FJ64GP306A-I/MR
DSPIC33FJ64GP306AT-E/MR
DSPIC33FJ64GP306AT-I/MR
DSPIC33FJ64GP706A-E/MR

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PCN_JAON-01PHJW963
CATALOG_PART_NBR
DSPIC33FJ64GP706A-I/MR
DSPIC33FJ64GP706AT-E/MR
DSPIC33FJ64GP706AT-I/MR
DSPIC33FJ64MC506A-E/MR
DSPIC33FJ64MC506A-H/MR
DSPIC33FJ64MC506A-I/MR
DSPIC33FJ64MC506AT-E/MR
DSPIC33FJ64MC506AT-H/MR
DSPIC33FJ64MC506AT-I/MR
DSPIC33FJ64MC706A-E/MR
DSPIC33FJ64MC706A-I/MR
DSPIC33FJ64MC706AT-E/MR
DSPIC33FJ64MC706AT-I/MR
MRF24WB0/MR
MRF24WB0T/MR
PIC18F67K22-E/MR
PIC18F67K22-I/MR
PIC18F67K22-I/MRRSL
PIC18F67K22T-I/MR
PIC18F67K22T-I/MRRSL
PIC18F67K90-E/MR
PIC18F67K90-I/MR
PIC18F67K90-I/MRRSL
PIC18F67K90T-I/MR
PIC24EP512GP806-E/MR
PIC24EP512GP806-I/MR
PIC24EP512GP806T-E/MR
PIC24EP512GP806T-I/MR
PIC24FJ128DA106-I/MR
PIC24FJ128DA206-I/MR
PIC24FJ128GA106-E/MR
PIC24FJ128GA106-E/MRC18
PIC24FJ128GA106-I/MR
PIC24FJ128GA106-I/MRC18
PIC24FJ128GA106T-I/MR
PIC24FJ128GB106-I/MR
PIC24FJ128GB106T-I/MR
PIC24FJ128GB206-I/MR
PIC24FJ192GA106-E/MR
PIC24FJ192GA106-I/MR
PIC24FJ192GB106-I/MR
PIC24FJ256DA106-I/MR
PIC24FJ256DA206-I/MR

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PCN_JAON-01PHJW963
CATALOG_PART_NBR
PIC24FJ256GA106-E/MR
PIC24FJ256GA106-I/MR
PIC24FJ256GA106T-E/MR
PIC24FJ256GA106T-I/MR
PIC24FJ256GB106-I/MR
PIC24FJ256GB106T-I/MR
PIC24FJ256GB206-I/MR
PIC24FJ256GB206T-I/MR
PIC24FJ64GB106-I/MR
PIC24HJ128GP206A-E/MR
PIC24HJ128GP206A-I/MR
PIC24HJ128GP206AT-E/MR
PIC24HJ128GP206AT-I/MR
PIC24HJ128GP306A-E/MR
PIC24HJ128GP306A-I/MR
PIC24HJ128GP306AT-E/MR
PIC24HJ128GP306AT-I/MR
PIC24HJ128GP506A-E/MR
PIC24HJ128GP506A-H/MR
PIC24HJ128GP506A-I/MR
PIC24HJ128GP506AT-E/MR
PIC24HJ128GP506AT-H/MR
PIC24HJ128GP506AT-I/MR
PIC24HJ64GP206A-E/MR
PIC24HJ64GP206A-I/MR
PIC24HJ64GP206A-I/MR031
PIC24HJ64GP206A-I/MRA28
PIC24HJ64GP206AT-E/MR
PIC24HJ64GP206AT-I/MR
PIC24HJ64GP206AT-I/MR031
PIC24HJ64GP206AT-I/MRA28
PIC24HJ64GP506A-E/MR
PIC24HJ64GP506A-I/MR
PIC24HJ64GP506AT-E/MR
PIC24HJ64GP506AT-I/MR
PIC32MX320F032H-40I/MR
PIC32MX320F032H-40V/MR
PIC32MX320F032HT-40I/MR
PIC32MX320F032HT-40V/MR
PIC32MX320F064H-40I/MR
PIC32MX320F064H-40V/MR
PIC32MX320F064H-80I/MR
PIC32MX320F064H-80V/MR

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PCN_JAON-01PHJW963
CATALOG_PART_NBR
PIC32MX320F064HT-40I/MR
PIC32MX320F064HT-40V/MR
PIC32MX320F064HT-80I/MR
PIC32MX320F064HT-80V/MR
PIC32MX320F128H-80I/MR
PIC32MX320F128H-80V/MR
PIC32MX320F128HT-80I/MR
PIC32MX320F128HT-80V/MR
PIC32MX340F128H-80I/MR
PIC32MX340F128H-80V/MR
PIC32MX340F128HT-80I/MR
PIC32MX340F128HT-80V/MR
PIC32MX340F256H-80I/MR
PIC32MX340F256H-80V/MR
PIC32MX340F256HT-80I/MR
PIC32MX340F256HT-80V/MR
PIC32MX340F512H-80I/MR
PIC32MX340F512H-80V/MR
PIC32MX340F512HT-80I/MR
PIC32MX340F512HT-80V/MR
PIC32MX420F032H-40I/MR
PIC32MX420F032H-40V/MR
PIC32MX420F032HT-40I/MR
PIC32MX420F032HT-40V/MR
PIC32MX440F128H-80I/MR
PIC32MX440F128H-80V/MR
PIC32MX440F128HT-80I/MR
PIC32MX440F128HT-80V/MR
PIC32MX440F256H-80I/MR
PIC32MX440F256H-80V/MR
PIC32MX440F256HT-80I/MR
PIC32MX440F256HT-80V/MR
PIC32MX440F512H-80I/MR
PIC32MX440F512H-80V/MR
PIC32MX440F512HT-80I/MR
PIC32MX440F512HT-80V/MR
PIC32MX575F256H-80I/MR
PIC32MX575F256H-80V/MR
PIC32MX575F256HT-80I/MR
PIC32MX575F256HT-80V/MR
PIC32MX575F512H-80I/MR
PIC32MX575F512H-80V/MR
PIC32MX575F512HT-80I/MR

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PCN_JAON-01PHJW963
CATALOG_PART_NBR
PIC32MX575F512HT-80V/MR
PIC32MX675F256H-80I/MR
PIC32MX675F256H-80V/MR
PIC32MX675F256HT-80I/MR
PIC32MX675F256HT-80V/MR
PIC32MX675F512H-80I/MR
PIC32MX675F512H-80V/MR
PIC32MX675F512HT-80I/MR
PIC32MX675F512HT-80V/MR
PIC32MX695F512H-80I/MR
PIC32MX695F512H-80I/MRD21
PIC32MX695F512H-80V/MR
PIC32MX695F512HT-80I/MR
PIC32MX695F512HT-80I/MRD21
PIC32MX695F512HT-80V/MR
PIC32MX775F256H-80I/MR
PIC32MX775F256H-80V/MR
PIC32MX775F256HT-80I/MR
PIC32MX775F256HT-80V/MR
PIC32MX775F512H-80I/MR
PIC32MX775F512H-80I/MRE21
PIC32MX775F512H-80V/MR
PIC32MX775F512HT-80I/MR
PIC32MX775F512HT-80V/MR
PIC32MX795F512H-80I/MR
PIC32MX795F512H-80V/MR
PIC32MX795F512HT-80I/MR
PIC32MX795F512HT-80V/MR
PIC32MZ0512EFE064-E/MR
PIC32MZ0512EFE064-E/MRA21
PIC32MZ0512EFE064-I/MR
PIC32MZ0512EFE064T-E/MR
PIC32MZ0512EFE064T-E/MRA21
PIC32MZ0512EFE064T-I/MR
PIC32MZ0512EFF064-E/MR
PIC32MZ0512EFF064-I/MR
PIC32MZ0512EFF064T-E/MR
PIC32MZ0512EFF064T-I/MR
PIC32MZ0512EFK064-E/MR
PIC32MZ0512EFK064-I/MR
PIC32MZ0512EFK064T-E/MR
PIC32MZ0512EFK064T-I/MR
PIC32MZ1024ECG064-I/MR

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PCN_JAON-01PHJW963
CATALOG_PART_NBR
PIC32MZ1024ECG064-I/MRDD9
PIC32MZ1024ECG064T-I/MR
PIC32MZ1024ECG064T-I/MRDD9
PIC32MZ1024ECH064-I/MR
PIC32MZ1024ECH064T-I/MR
PIC32MZ1024ECM064-I/MR
PIC32MZ1024ECM064T-I/MR
PIC32MZ1024EFE064-E/MR
PIC32MZ1024EFE064-I/MR
PIC32MZ1024EFE064T-E/MR
PIC32MZ1024EFE064T-I/MR
PIC32MZ1024EFF064-E/MR
PIC32MZ1024EFF064-I/MR
PIC32MZ1024EFF064T-E/MR
PIC32MZ1024EFF064T-I/MR
PIC32MZ1024EFG064-E/MR
PIC32MZ1024EFG064-I/MR
PIC32MZ1024EFG064T-E/MR
PIC32MZ1024EFG064T-I/MR
PIC32MZ1024EFH064-E/MR
PIC32MZ1024EFH064-I/MR
PIC32MZ1024EFH064T-E/MR
PIC32MZ1024EFH064T-I/MR
PIC32MZ1024EFK064-E/MR
PIC32MZ1024EFK064-I/MR
PIC32MZ1024EFK064T-E/MR
PIC32MZ1024EFK064T-I/MR
PIC32MZ1024EFM064-E/MR
PIC32MZ1024EFM064-I/MR
PIC32MZ1024EFM064T-E/MR
PIC32MZ1024EFM064T-I/MR
PIC32MZ2048ECG064-I/MR
PIC32MZ2048ECG064T-I/MR
PIC32MZ2048ECH064-I/MR
PIC32MZ2048ECH064-I/MREE9
PIC32MZ2048ECH064T-I/MR
PIC32MZ2048ECH064T-I/MREE9
PIC32MZ2048ECM064-I/MR
PIC32MZ2048ECM064T-I/MR
PIC32MZ2048EFG064-E/MR
PIC32MZ2048EFG064-I/MR
PIC32MZ2048EFG064T-E/MR
PIC32MZ2048EFG064T-I/MR

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PCN_JAON-01PHJW963
CATALOG_PART_NBR
PIC32MZ2048EFH064-E/MR
PIC32MZ2048EFH064-I/MR
PIC32MZ2048EFH064T-E/MR
PIC32MZ2048EFH064T-I/MR
PIC32MZ2048EFM064-E/MR
PIC32MZ2048EFM064-I/MR
PIC32MZ2048EFM064T-E/MR
PIC32MZ2048EFM064T-I/MR
PIC24FJ64GA106-E/MR
PIC24FJ64GA106-I/MR
PIC24FJ64GA106T-I/MR
PIC24FJ64GA106T-I/MR029
PIC24FJ64GA106T-I/MR032
PIC24FJ64GA106T-I/MR033
PIC24FJ64GA106T-I/MR035